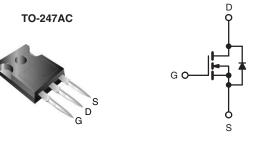


Vishay Siliconix

## **S Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650			
R <sub>DS(on)</sub> max. at 25 °C (Ω)	V <sub>GS</sub> = 10 V	0.07		
Q <sub>g</sub> max. (nC)	216			
Q <sub>gs</sub> (nC)	39			
Q <sub>gd</sub> (nC)	57			
Configuration	Single			



N-Channel MOSFET

#### **FEATURES**

- Generation One
- Low Figure-of-Merit R<sub>on</sub> x Q<sub>g</sub>
- 100 % Avalanche Tested
- Ultra Low Gate Charge
- Ultra Low Ron
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

- PFC Power Supply Stages
- Hard Switching Topologies
- Solar Inverters
- UPS
- Motor Control
- Server Telecom

ORDERING INFORMATION			
Package	TO-247AC		
Lead (Pb)-free	SiHG47N60S-E3		

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			LIMIT	UNIT		
Drain-Source Voltage			600			
Gate-Source Voltage			± 20	V		
Gate-Source Voltage AC (f > 1 Hz)			30			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	$V_{GS}$ at 10 V $T_C = 25 ^{\circ}C$	I_	47			
	$V_{GS}$ at 10 V $T_C = 100 ^{\circ}\text{C}$	l <sub>D</sub>	30	Α		
Pulsed Drain Current <sup>a</sup>			140			
Linear Derating Factor			3.3	W/°C		
Avalanche Energy (repetitive)			0.42	!		
Single Pulse Avalanche Energy <sup>b</sup>			1800	mJ		
Maximum Power Dissipation			417	W		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	°C		
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C	d\//d+	37	V/ns		
Reverse Diode dV/dt <sup>d</sup>		dV/dt	8.5	V/115		
Soldering Recommendations (Peak Temperature)	for 10 s		300	°C		

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 73.5 mH,  $R_g$  = 25  $\Omega,\,I_{AS}$  = 7 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	$R_{thJA}$	-	40	°C/W	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.3	C/VV	

PARAMETER	SYMBOL	TEST (	MIN.	TYP.	MAX.	UNIT	
Static		•				l	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$	600	-	-	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference t	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.7	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	$V_{DS} = V$	<sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>G</sub>	V <sub>GS</sub> = ± 20 V		-	± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C		-	1	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = 000 \text{ V}, \text{ V}$	I <sub>D</sub> = 24 A	-	0.057	0.07	Ω
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = 8 V, I <sub>D</sub> = 3 A		7.5	-	S
Dynamic		_			l	l	
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$		-	6630	-	pF
Output Capacitance	Coss			-	220	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	7	-	
Total Gate Charge	Qg			-	180	216	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 20 \text{ A}, V_{DS} = 400 \text{ V}$	-	39	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			-	57	-	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD} = 380 \text{ V}, I_{D} = 47 \text{ A},$ $R_{g} = 4.4 \Omega, V_{GS} = 13 \text{ V}$		-	30	60	ns
Rise Time	t <sub>r</sub>			-	12	25	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	115	175	
Fall Time	t <sub>f</sub>			-	9	20	
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		1	0.62	-	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	Is	,	MOSFET symbol		-	47	
Pulsed Diode Forward Current	I <sub>SM</sub>	showing the integral reverse p - n junction diode		-	-	140	Α
Body Diode Voltage	$V_{SD}$	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 47 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> , dI/dt = 100 A/μs, V <sub>R</sub> = 25 V		-	750	1125	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	18	36	μC
Body Diode Reverse Recovery Current	I <sub>RRM</sub>			-	39	80	Α



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

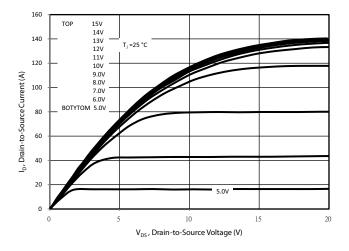


Fig. 1 - Typical Output Characteristics (TO-247)

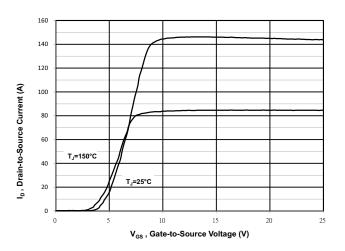


Fig. 3 - Typical Transfer Characteristics

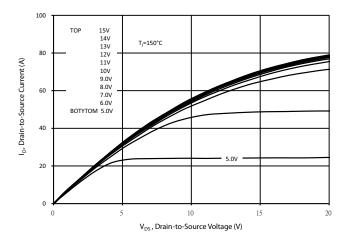


Fig. 2 - Typical Output Characteristics (TO-247)

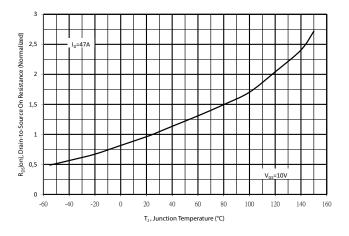


Fig. 4 - Normalized On-Resistance vs. Temperature



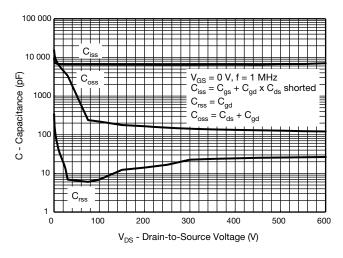


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

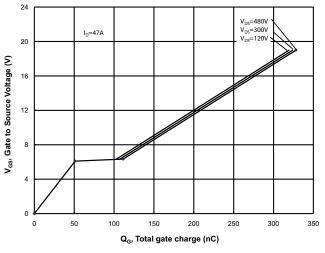


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

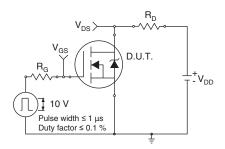


Fig. 9a - Switching Time Test Circuit

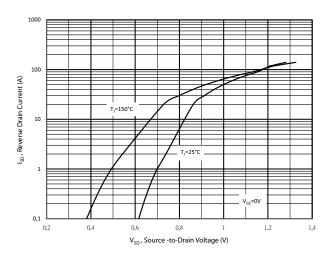


Fig. 7 - Typical Source-Drain Diode Forward Voltage

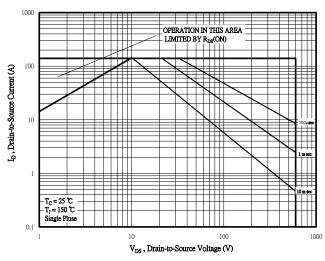


Fig. 8 - Maximum Safe Operating Area

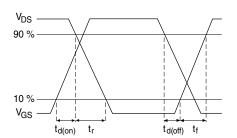


Fig. 9b - Switching Time Waveforms



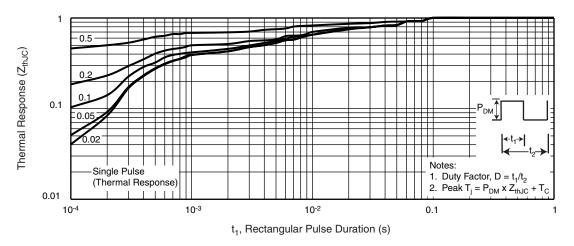


Fig. 10 - Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-247AC)

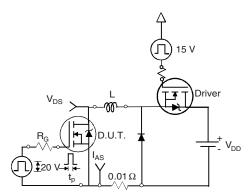


Fig. 11a - Unclamped Inductive Test Circuit

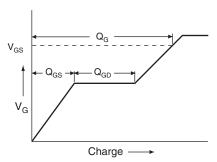


Fig. 12a - Basic Gate Charge Waveform

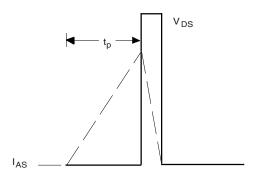


Fig. 11b - Unclamped Inductive Waveforms

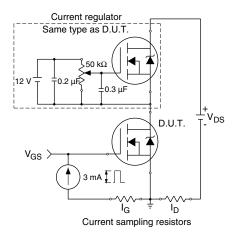
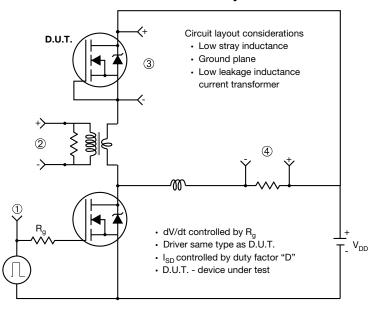


Fig. 12b - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



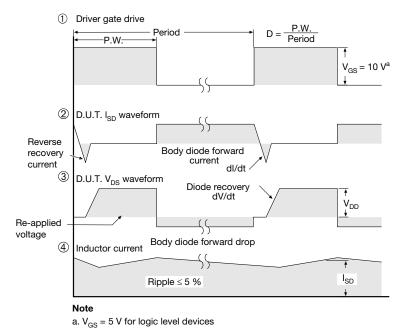


Fig. 13 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?91341">www.vishay.com/ppg?91341</a>.



# **Legal Disclaimer Notice**

Vishay

## **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

# **Material Category Policy**

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000